Exhibition fees

<table>
<thead>
<tr>
<th>Category</th>
<th>1 booth/ 75m²</th>
<th>Non-Members</th>
<th>¥375,000</th>
</tr>
</thead>
<tbody>
<tr>
<td>Members</td>
<td></td>
<td>¥320,000</td>
<td></td>
</tr>
</tbody>
</table>

* Members of the WECC member associations
  - (CPCA, EIPC, ELCKA, HKPCA, IPC, JPCA, KPCA and TPCA)
  - Booth area is change from 9m² to 75m²
  - Booth construction, cleaning, electricity, Water Supply, etc. is not included in the exhibition fee.

Exhibit Fee Payment

- Non-Members: ¥375,000 (including partial fees)
- Members: ¥320,000 (excluding partial fees)

Expiration of payment:

- From February 2 onward 100% of booth fees

Deadline

- January 31, 2020

Cancellation charges

- If an exhibit is cancelled to suit the exhibitor’s circumstances, cancellation charges (full or partial fees) shall apply as below.

| Date of receipt of written notice of cancellation | Cancellation charges
<table>
<thead>
<tr>
<th></th>
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</thead>
<tbody>
<tr>
<td>until February 1</td>
<td>50% of booth fees</td>
</tr>
<tr>
<td>From February 2 onward</td>
<td>100% of booth fees</td>
</tr>
</tbody>
</table>

How to apply

Please fill out the Application Form in consideration with the following:

- Carefully read the “Exhibition Regulations”
- Select the exhibition based on your product

The Secretariat Office will send the invoice or exhibitor who apply on the online will be able to download from exhibitor portal. Based on the invoice, please make the payment by the due date.

Schedule prior to the Exhibition (Tentative)

<table>
<thead>
<tr>
<th>January</th>
<th>February</th>
<th>April</th>
<th>May</th>
</tr>
</thead>
<tbody>
<tr>
<td>Application deadline</td>
<td>February 18 Exhbitors’ Briefing (Tokyo) February 20 Exhibitors’ Briefing (Osaka)</td>
<td>Sending invitations Mid-April</td>
<td>Deadline for submission of application documents Starting registration to the exhibition Last-April</td>
</tr>
<tr>
<td>May 25 to 26 installation period</td>
<td>May 27 to 29 Exhibition open * Immediate removal on the last day</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Specialty exhibitions

- The Exhibition Guide
- The Exhibition Guide
- The Exhibition Guide
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- The Exhibition Guide

[venue: Aomi Exhibition Hall]

Use of the venue is restricted due to the Olympic and Paralympic Games Tokyo 2020. The exhibition area is 80% shrink from the previous show. We might not accept increasing the number of booths or request to decrease the number of booths. Thank you for your corporation.

Booth type

<table>
<thead>
<tr>
<th>(A) Inline</th>
<th>(B) Block (four or more units)</th>
<th>(C) Island (20 or more units)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Width:</td>
<td>Length:</td>
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</tbody>
</table>

Exhibit Fee Payment

- Payment of exhibition fees will be due upon receipt of written notice of acceptance.

Promotion services will provide an opportunity to increase your presence at the exhibition.

Package booth

- Price: ¥73,000 (excluding tax)
- Materials: System panel
- Specifications and prices are subject to change.

Organizers:


Sponsor:

Ministry of Economy, Trade and Industry.
Comprehensive exhibition of technology embodying 5G, automobile, IoT, robots, wearable, etc.

- Highly specialized and focused
- Exhibition of large attendance from all over the world

**Aomi Exhibition Hall / TFT Hall Access**

- Organizer: Japan Robot Association
- Co-organizers: Japan Electronics Packaging and Circuits Association

**Floor Layout (Tentative)**

Please take the free shuttle during the exhibition. Details will be informed on the website.

*Please note that the floor layout is tentative.*

**Exhibitions held inside the exhibition/relevant exhibits**

**Electronic circuit technologies**
- [HEMT Tech](#)
- [Module JAPAN](#)
  - Flexible printed circuit board mounting / General technology for heat sink parts / Printed Products / Related Products / Design / Reliability Inspection / Materials / Functional Materials / Related equipment / Related systems
- [Flexible Printed Circuits Products Area](#)
  - General technology for Flexible Printed Circuits (Manufacturing)
- [EMS Japan](#)
  - General technological services related to EMS: Electronic electrical equipments, and Semiconductors

**High-density packaging technologies**
- [JPCA Show](#)
  - [24th Advanced Electronics Packaging Exhibition](#)
  - General technology for implementation and electronic technology (Materials) Circuit and Mounting design / High speed high frequency, high density, high precision mounting, Mounting technologies, Mounting technology
  
**Electrical Component Packaging Technologies**
- [JISSO Show](#)
  - [21st Japan Process Technology Exhibition](#)
  - General technology for Electronic Component Packaging Technologies (Electronics components, electronics mounted technologies, Semiconductor manufacturing, Mounting system, Inspection technology, Meeting design system, Robots)
  
**New circuit fabrication technology**
- [Total Organic Electronics Expo](#)
  - General technology for Organic Devices (Products and parts of Printed Electronics / MEMS) / Sensor LED / OLED / Applied products for Organic semiconductor

**Electro-optical Interconnection**
- [Total Organic Electronics Expo](#)
  - General introduction technology for using wire and cable (network equipment) / Electrical wire, cable and connector / Electrical wire processing equipment / Wiring material, Wiring harness / Measuring instruments for electrical wire and cable / Protection device / Diagnostic equipment

**Electrical/optical transmission technology**
- [Total Organic Electronics Expo](#)
  - General technology for Sensor and Sensing Systems (Sensor) / Semiconductors / Parts and Devices / Electronic Communication Devices / Network Systems / Software, Data, Remote, Power Source, Communication Devices, Technologies

**Sensor technology**
- [Total Organic Electronics Expo](#)

**Semiconductors and Electronic Parts**
- [Total Organic Electronics Expo](#)
  - General technology for Semiconductors and Electronic parts

**Highly functional textile**
- [E-Textile](#)
  - A mix of textiles technology, fiber and knitting (General technology for smart textile, stretchable and wearable (Textile material) conductive material / material: knitting / weaving technology / Print marking technology / Fiber)

**Co-organizers**
- Japan Electronics Packaging and Circuits Association
- E-Textile research group of Fukui Sangyo Times Inc.